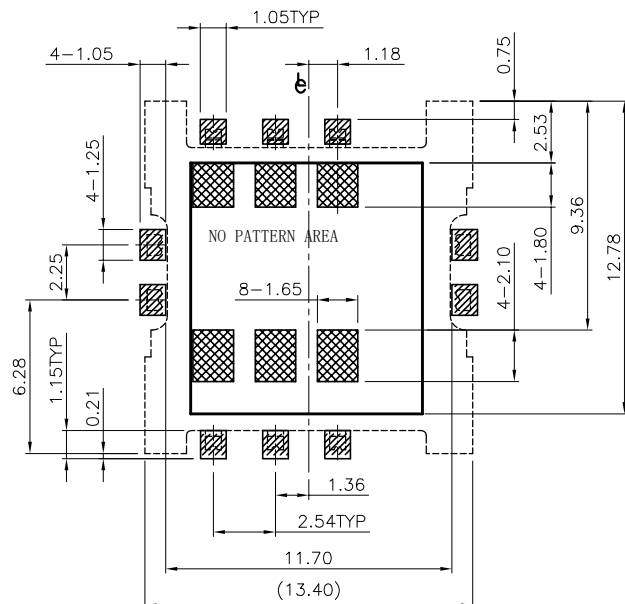
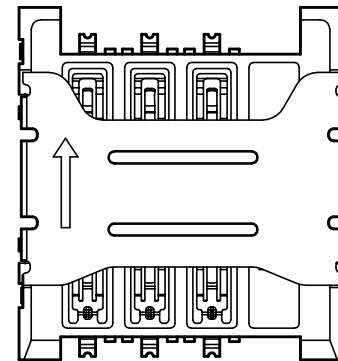
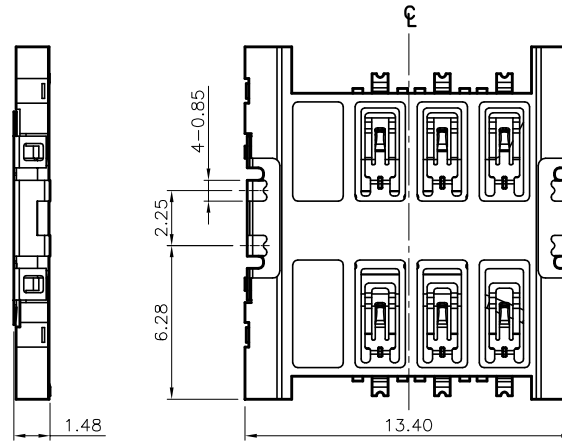
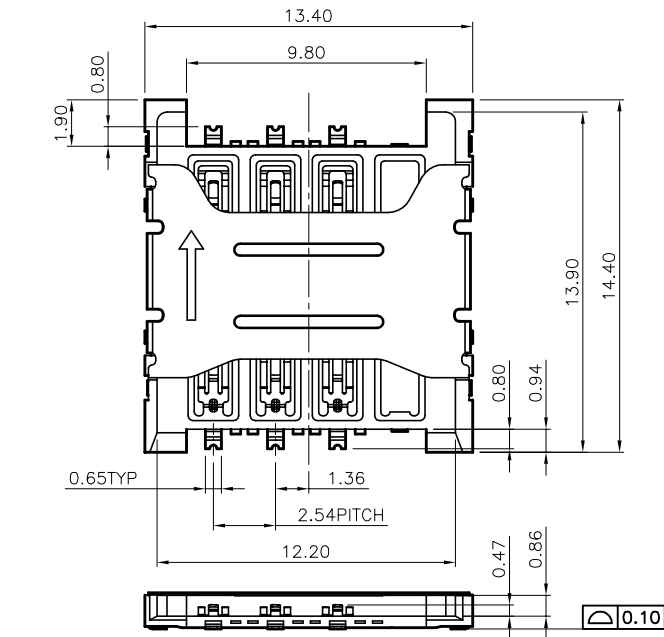



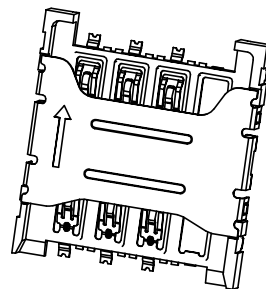


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2011/10/31



RECOMMENDED P.C.B. LAYOUT
TOLERANCE: ± 0.05 TOP VIEW

-  PCB AREA
 CONNECT AREA
 KEEP OUT AREA



MATERIALS

1. HOUSING : THERMOPLASTIC (UL 94V-0) .
2. TERMINAL : COPPER ALLOY,
PLATING : GOLD PLATED ON CONTACT AREA
AND SOLDER TAILS,NICKEL PLATED OVERALL.
3. SHELL : STAINLESS STEEL.
PLATING : NICKEL PLATED OVERALL.
GOLD PLATED ON SOLDER TAILS

SPECIFICATION

1. CURRENT RATING : 1.0 A MAX.
2. DIELECTRIC WITHSTANDING VOLTAGE :
500V AC R.M.S. FOR ONE MINUTE.
3. INSULATION RESISTANCE : 1000M次MIN. AT 500V DC.
4. CONTACT RESISTANCE : 30m次MAX.
5. OPERATING TEMPERATURE : -40°C TO +85°C.

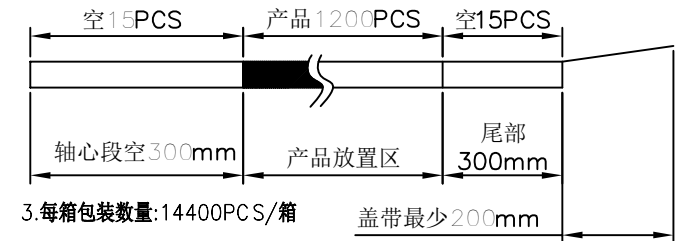
DESCRIPTION OF PLATING ON TERMINALS			
NO.	EXPLAIN	NO.	EXPLAIN
0	GOLD FLASH	3	GOLD 15u"
1	GOLD 5u"	4	GOLD 20u"
2	GOLD 10u"	6	GOLD 30u"

GENERAL TOLERANCE				DWG NO.			APPD:	WIND	Scale	1:1
X.±0.45		x.°±5°		Title	MICRO SIM SOCKET 6PIN 1.50H (焊接脚内折防溃PIN)	CHKD:			UNIT	mm
.X±0.35		.x°±2°					DR:			
.XX±0.25		.xx°±1°		Part NO.	5001B-SIM150-090	Date	2012/02/29			
.XXX±0.15		.xxx°±0.5°				东莞市文章济美电子有限公司				
SHEET	1/1									

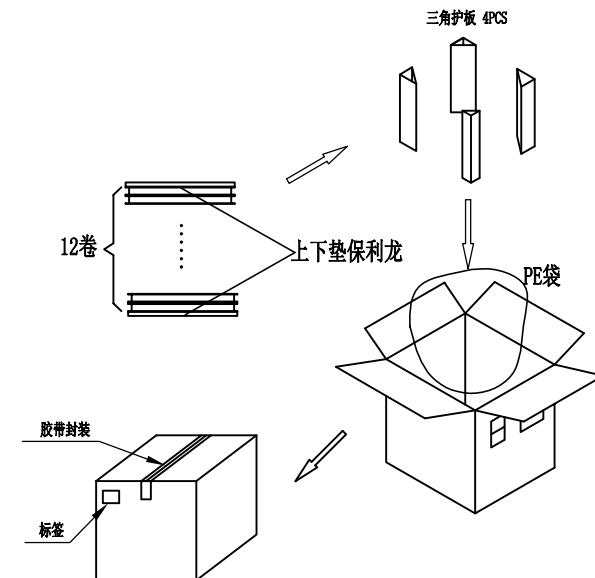
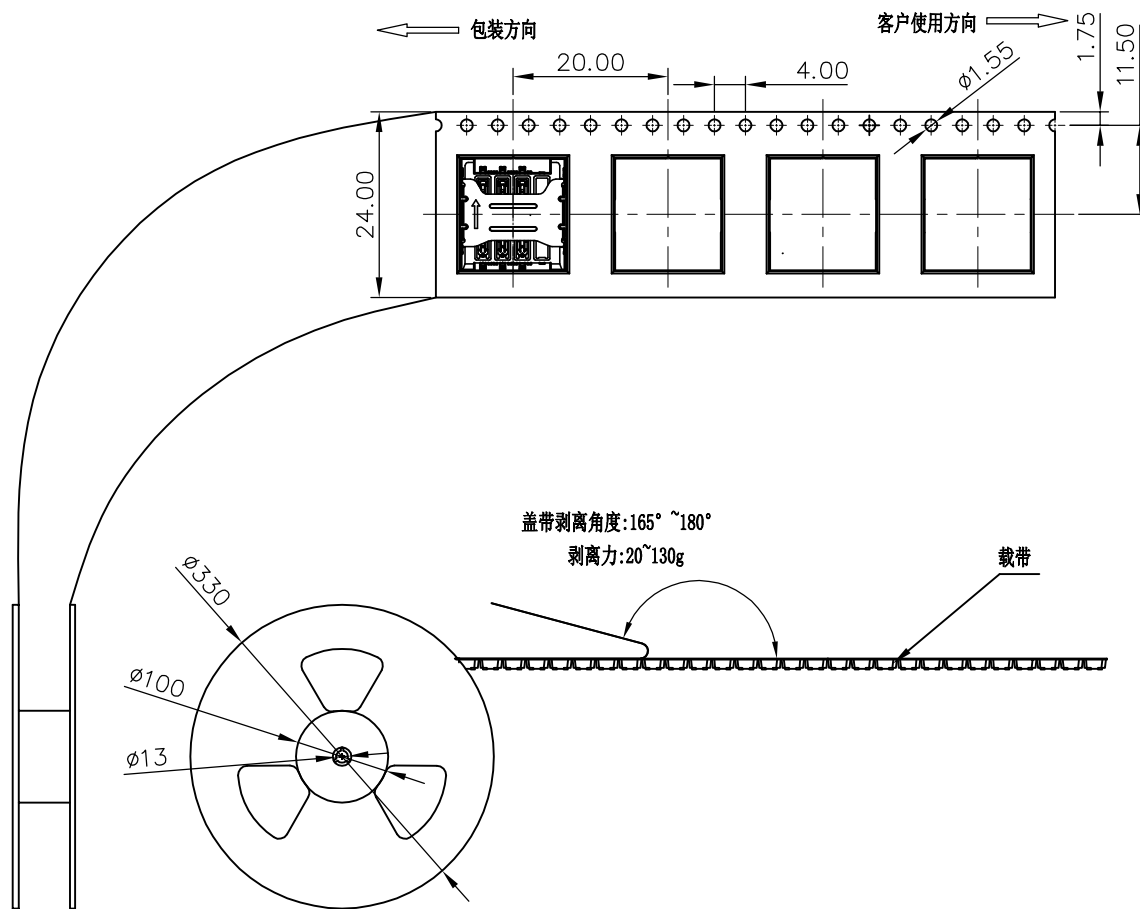
REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2012/04/13


NOTES

1. 每卷包装数量:1200PCS/每卷
2. 卷带包装方式:



- 3.每箱包装数量:14400PCS/箱
- 4.纸箱规格: 340*340*390MM, 材质: K=K



GENERAL TOLERANCE		DWG NO.	5001B-SIM150-090		APPD:	WIND	Scale	1:1
X.±0.45	x.±5°	Title	MICRO SIM CARD 6P 1.5H 包装图		CHKD:		UNIT	mm
.X±0.35	.x±2°				DR:			
.XX±0.25	.xx±1°	Part NO.			Date	2012/04/13		
.XXX±0.15	.xxx±0.5°							
SHEET	1/1		东莞市文章济美电子有限公司					